SYSTEM AND METHOD FOR REINFORCING A BOND PAD

ABSTRACT OF THE DISCLOSURE

The reinforcing system (10, 70, 90) for a bond pad (12, 72, 92) includes at least one dielectric layer or stack (20, 21, 22, 76, 78, 96, 98) disposed under the bond pad (12, 72, 92). A reinforcing patterned structure (30, 80, 82, 100, 102) is disposed in the dielectric layer or stack (20, 21, 22, 76, 78, 96, 98).

Figure 1